

ABSTRACT OF THE DISCLOSURE

5 *50C37* A resin sealed electronic device has an electronic element (30), a first external lead (10) with an element placement pad (11) having a thickness t of less than 0.1 mm, and a second external lead (20), which is disposed at a distance from the element placement pad (11), the first external lead (10) being bent into an S shape, the bending depth d thereof being made at least the thickness t of the first external lead (10), and the thickness T of the sealing resin on the non-element side of the element placement pad (11) being made smaller than the bending depth d . The electronic element (30), part of the first external lead (10), and part of the second external lead (20) are sealed by a sealing resin (40). This structure provides a compact electronic device, the vertical, horizontal, and height dimensions of which are all under 1 mm.

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